

AF/IRW



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Marc Schaepkens, et al.

Serial No.: 10/817,531

Filed: April 2, 2004

For: Organic Electronic Packages Having
Hermetically Sealed Edges and
Methods of Manufacturing Such
Packages

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Group Art Unit: 2815

Examiner: Chris C. Chu

Atty. Docket: 133525-1/YOD/MAN
GERD:0065

Mail Stop Appeal Brief - Patents
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P.O. Box 1450
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October 10, 2007 Date	 Jessie Hebert

RESPONSE TO NOTICE OF NON-COMPLIANT APPEAL BRIEF

This Paper is being submitted in response to the Notice of Non-Compliant Appeal Brief that was mailed on September 10, 2007. The Notice indicated that Section 3 (Status of Claims) and Section 5 (Summary of Claimed Subject Matter) contained minor errors. The Notice also indicated that the Appeal Brief need not be re-submitted in its entirety to correct the minor defects, but that only those sections with errors need to be re-submitted. Accordingly, by this Paper, Appellants re-submit the above-referenced sections and request that these sections be used to replace the previous submission. Specifically, Section 3 has been amended to reflect the prior cancellation of claims 34-46. Section 5 has been amended such that citation of "claim 1" has been replaced with "claim 47" in paragraph 4 to correct the typographical error.

3. **STATUS OF CLAIMS**

Claims 1-10, 47-50 are currently under final rejection and, thus, are the subject of this appeal. Claims 11-33 are withdrawn from consideration. Claims 34-46 have been canceled.

5. **SUMMARY OF CLAIMED SUBJECT MATTER**

Embodiments of the present application generally relate to providing a hermetically sealed package for organic electronic devices. Application, Page 2, paragraph [0005]. In one embodiment an organic electronic package is provided, wherein the package includes a sealant implemented to couple a superstrate to a flexible substrate, providing a complete enclosure for the organic electronic device. Application, Page 7, paragraph [0024]. As used in the present specification, the “organic electronic device” includes a number of organic semiconductor layers disposed between two conductors or electrodes. Application, Page 7, paragraph [0023]. The specification describes a superstrate as referring to upper substrate of the organic package. Application, Page 7, paragraph [0025]. In one embodiment, the organic package includes an organic electronic device and a superstrate disposed proximate to the organic electronic device, wherein the superstrate is adapted to wrap around the edges of the package, thereby sealing and protecting the organic electronic device. Application, Page 9, paragraphs [0028] – [0029], Fig. 3.

The Application contains two (2) independent claims, namely, claims 1 and 47, of which are the subject of this Appeal. The subject matter of these claims is summarized below.

With regard to the aspect of the invention set forth in independent claim 1, discussions of the recited features of claim 1 can be found at least in the below cited locations of the specification and drawings. By way of example, an embodiment in accordance with the present invention relates to a package (e.g., 22). *See e.g.*, Application, paragraph [0005]; Fig. 3. The package (e.g., 22) comprises a flexible substrate (e.g., 12) comprising a polymeric transparent film. *See e.g.*, Application, paragraphs [0018]-[0019]; Fig. 3. The package (e.g., 22) further comprises an organic electronic device (e.g., 16) coupled to the transparent film. *See e.g.*, Application, paragraph [0023]; Fig. 3. The package (e.g., 22) further comprises a sealant (e.g., 18) coupled to the flexible substrate (e.g., 12) and disposed about the perimeter of the organic electronic device (e.g., 16). *See e.g.*, Application, paragraph [0024]; Fig. 3. The package (e.g., 22) further

comprises a superstrate (e.g., 24) coupled directly to the sealant (e.g., 18) and disposed proximate to the organic electronic device (e.g., 16), wherein the superstrate (e.g., 24) comprises a periphery adapted to wrap around the edges of the package (e.g., 22). *See e.g.*, Application, paragraphs [0025], [0026], [0028] and [0029]; Fig. 3.

With regard to the aspect of the invention set forth in independent claim 47, discussions of the recited features of claim 47 can be found at least in the below cited locations of the specification and drawings. By way of example, an embodiment in accordance with the present invention relates to a package (e.g., 22). *See e.g.*, Application, paragraph [0005]; Fig. 3. The package (e.g., 22) comprises a flexible substrate (e.g., 12) comprising a polymeric transparent film. *See e.g.*, Application, paragraphs [0018]-[0019]; Fig. 3. The package (e.g., 22) further comprises an organic electronic device (e.g., 16) coupled to the transparent film. *See e.g.*, Application, paragraph [0023]; Fig. 3. The package (e.g., 22) further comprises a sealant (e.g., 18) coupled to the flexible substrate (e.g., 12) and disposed about the perimeter of the organic electronic device (e.g., 16). *See e.g.*, Application, paragraph [0024]; Fig. 3. The package (e.g., 22) further comprises a superstrate (e.g., 24) coupled directly to the sealant (e.g., 18) and disposed proximate to the organic electronic device (e.g., 16), wherein the superstrate (e.g., 24) comprises at least one layer larger than the flexible substrate (e.g., 12) and a periphery adapted to wrap around the edges of the package (e.g., 22). *See e.g.*, Application, Page 2, paragraph [0005]. *See e.g.*, Application, paragraphs [0025], [0026], [0028] and [0029]; Fig. 3.

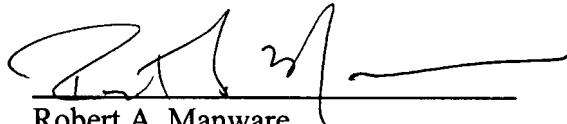
These claims are clearly different and patentably distinction from the prior art, as discussed below.

Conclusion

Appellants respectfully submit that with the above-referenced replacement sections, the Appeal Brief is now complete and fully compliant with the requirements under 37 CFR 41.37, and thus request that the case be passed to the Board for consideration. However, if the Examiner or Board wishes to resolve any other issues by way of a telephone conference, the Examiner or Board is kindly invited to contact the undersigned attorney at the telephone number indicated below.

Date: October 10, 2007

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'R. A. Manware', written over a horizontal line.

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